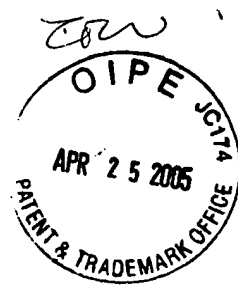


Docket No.: 050352-0020

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 20277  
 :  
 Shiroshi MATSUKI, et al. : Confirmation Number: 9915  
 :  
 Application No.: 09/944,344 : Group Art Unit: 1753  
 :  
 Filed: September 04, 2001 : Examiner: Edna Wong  
 :

For: MATERIAL FOR COPPER ELECTROPLATING, METHOD FOR MANUFACTURING SAME AND COPPER ELECTROPLATING METHOD

Mail Stop Amendment  
 Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

Dear Sir:

Transmitted herewith is an Amendment in the above-identified application.

- No additional fee is required.
- Applicant is entitled to small entity status under 37 CFR 1.27
- Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	17	20	0	\$50.00 =	\$0.00
Independent Claims	8	8	0	\$200.00 =	\$0.00
Multiple dependent claims newly presented					\$0.00
Fee for extension of time					\$0.00
					\$0.00
Total of Above Calculations					\$0.00

- Please charge my Deposit Account No. 500417 in the amount of \$0.00. An additional copy of this transmittal sheet is submitted herewith.
- The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 500417, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

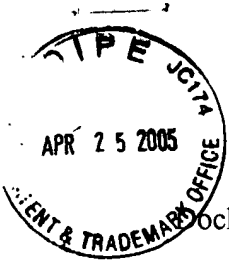
McDERMOTT WILL & EMERY LLP

*Cameron K. Weiffenbach*  
 Cameron K. Weiffenbach  
 Registration No. 44,488

600 13<sup>th</sup> Street, N.W.  
 Washington, DC 20005-3096  
 Phone: 202.756.8000 CKW/dlb  
 Facsimile: 202.756.8087  
**Date: April 25, 2005**

Please recognize our Customer No. 20277  
 as our correspondence address.

40



ocket No.: 050352-0020

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of	:	Customer Number: 20277
	:	
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For: MATERIAL FOR COPPER ELECTROPLATING, METHOD FOR MANUFACTURING SAME AND COPPER ELECTROPLATING METHOD

**AMENDMENT and REQUEST FOR RECONSIDERATION**  
**UNDER 37 CFR § 1.111**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is a response to the non-final Office Action dated January 25, 2005. The above-referenced patent application has been amended as set forth below.

Please amend claim 1 as set forth in the "Amendments to the Claims" on pages 2 to 5 of this response.